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Min et al.

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(54) **PORTION OF SUBSTRATE FOR LED PACKAGE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D26/1, 2; 257/79, 80,
257/81, 88, 89, 95, 98, 99, 100, E33.058;
313/483, 498, 500; 362/555, 800
See application file for complete search history.

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(57) **CLAIM**

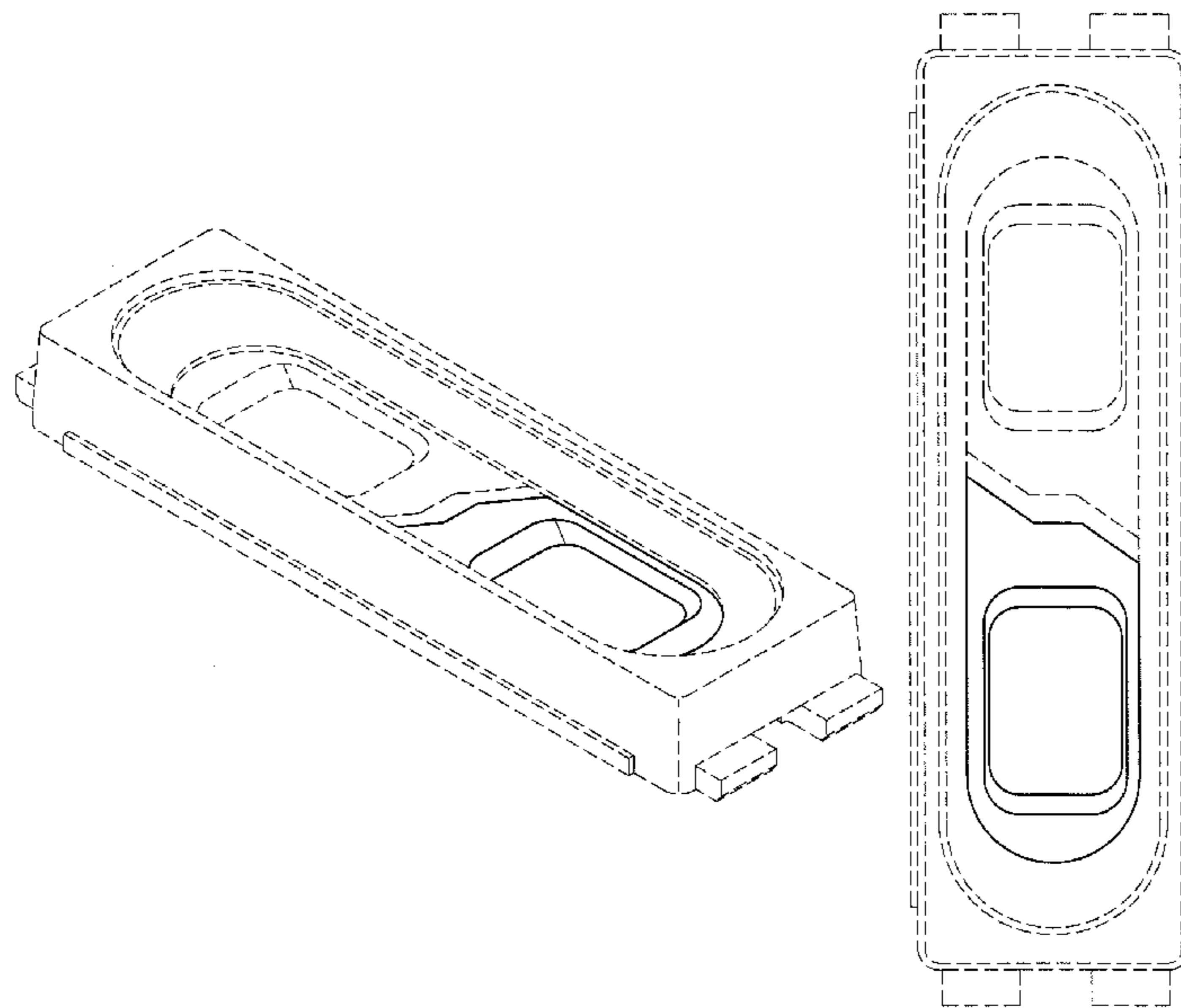
The ornamental design for a portion of substrate for LED package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of the portion of substrate for LED package showing our new design;
FIG. 2 is a front view thereof, the rear view being a mirror image thereof;
FIG. 3 is a left side view thereof, the right side view being a mirror image thereof;
FIG. 4 is a top plan view thereof;
FIG. 5 is a bottom plan view thereof; and,
FIG. 6 is a cross-sectional reference view thereof through VI-VI of FIG. 2.

The broken lines shown are included for the purpose of illustrating the unclaimed portions of the article and form no part of the claim.

1 Claim, 3 Drawing Sheets



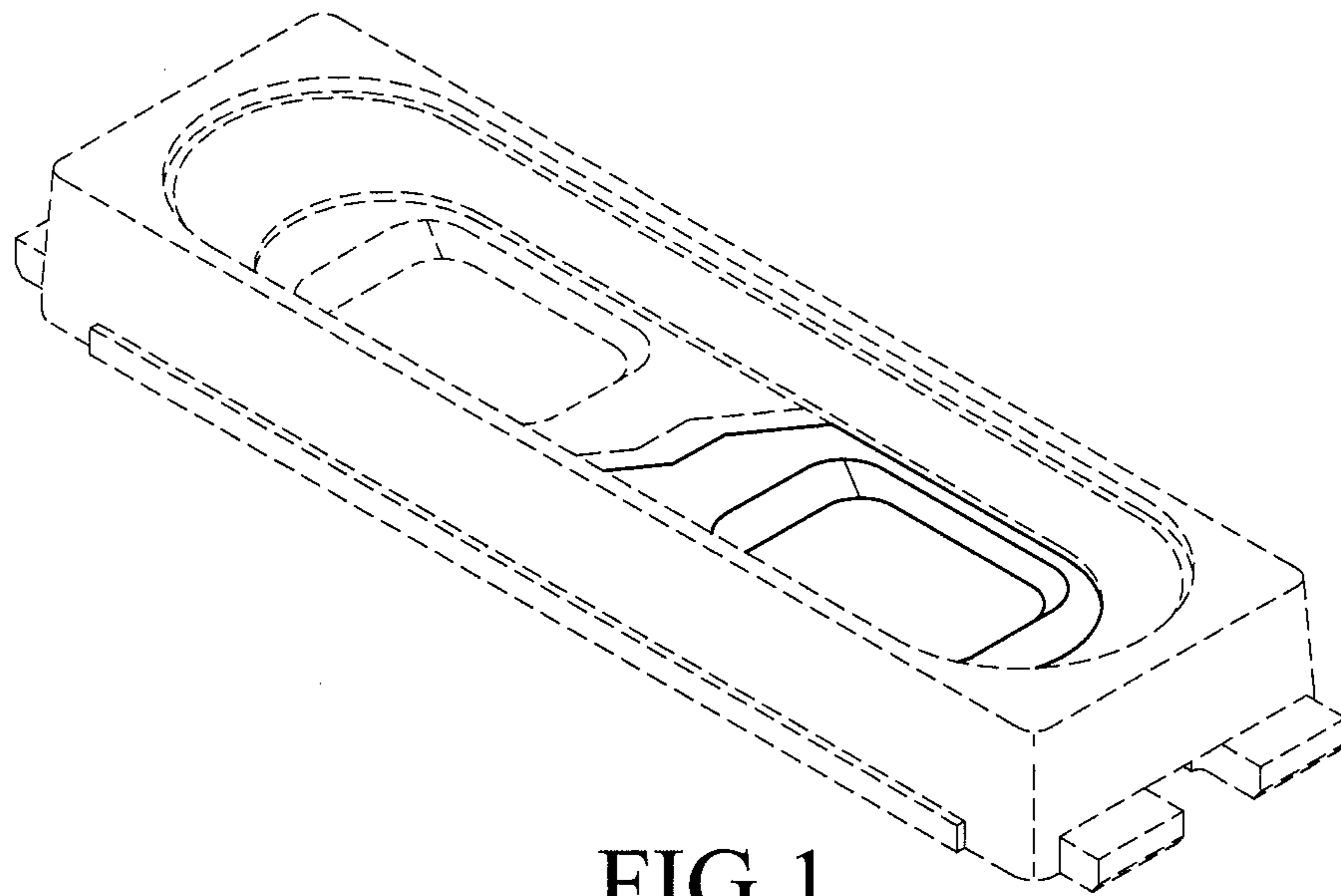


FIG. 1

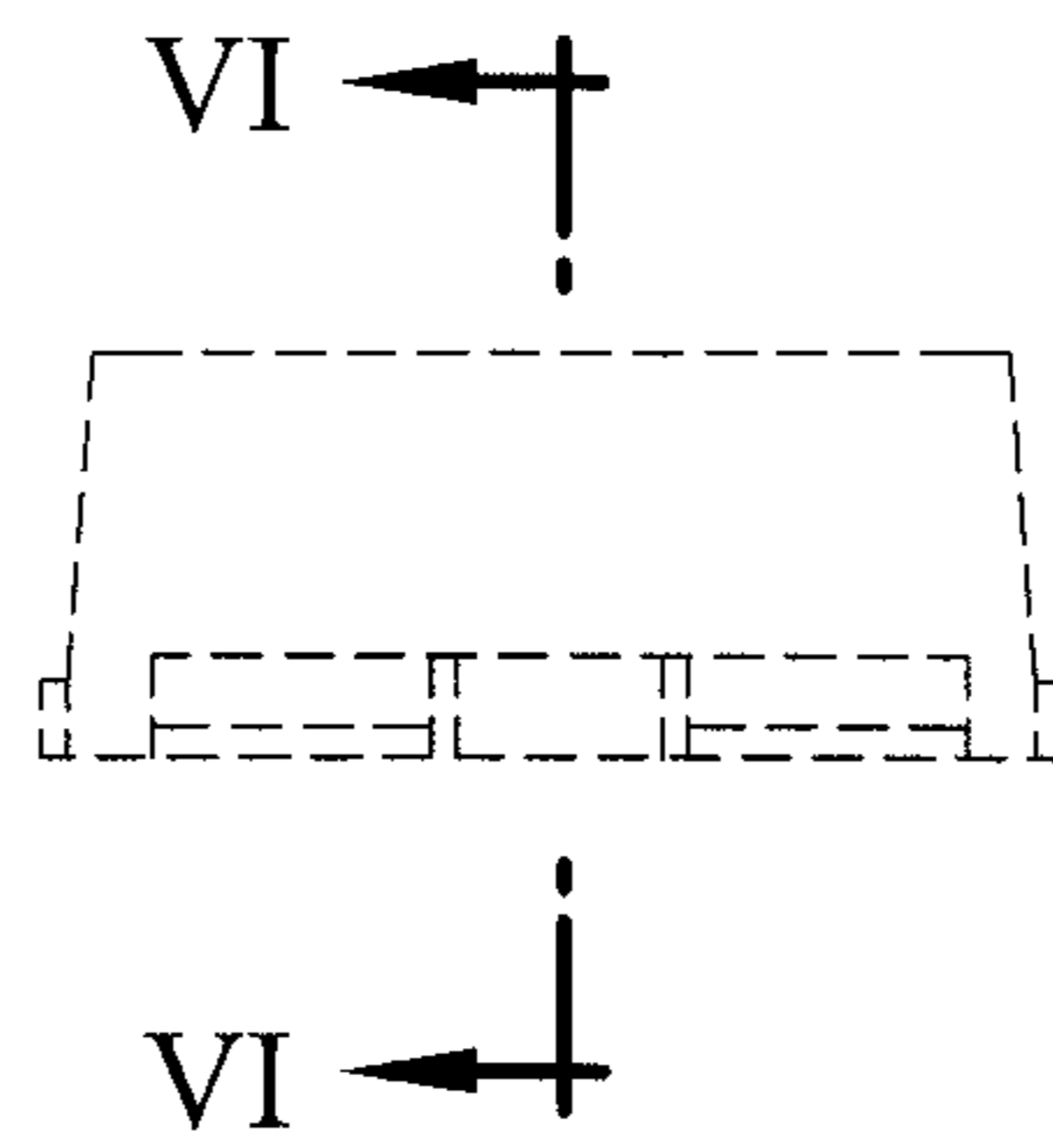


FIG. 2



FIG. 3

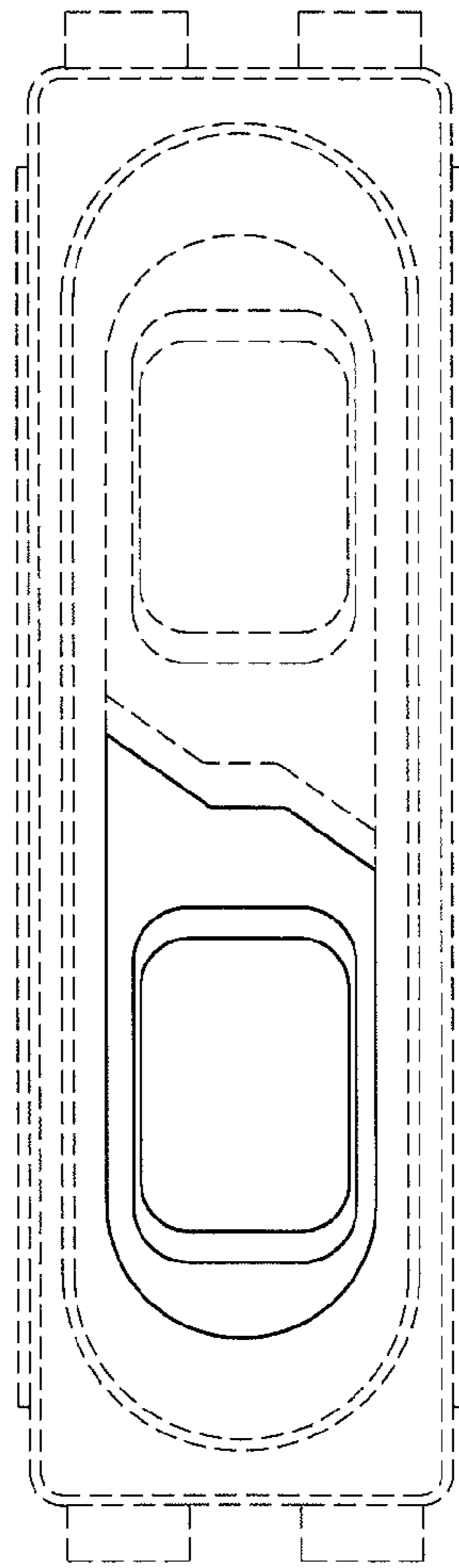


FIG.4

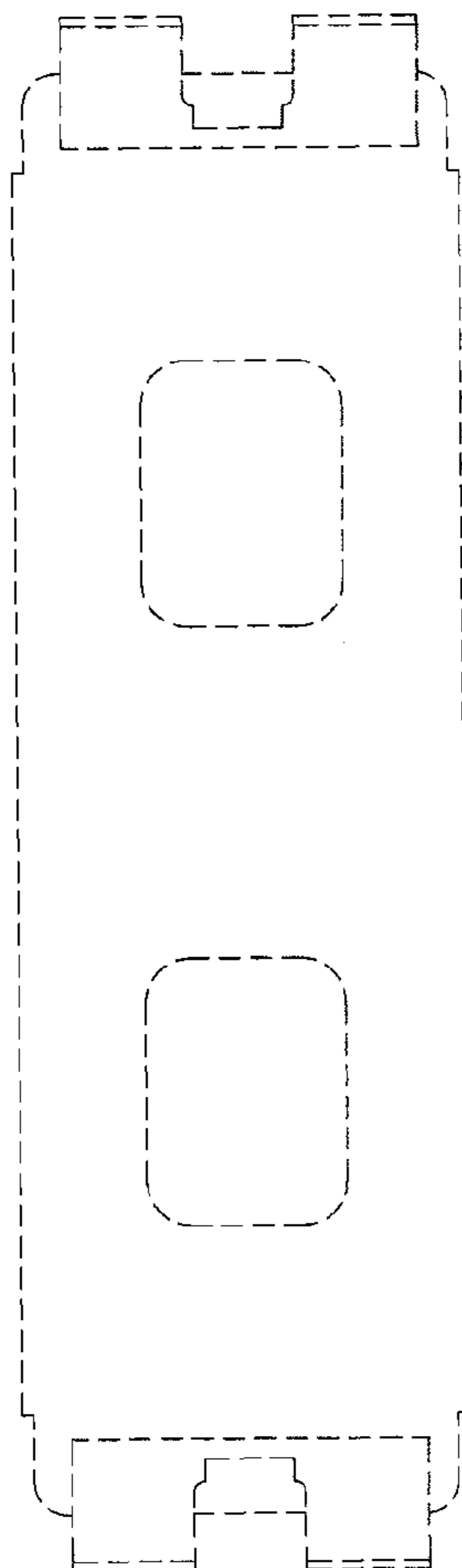


FIG. 5

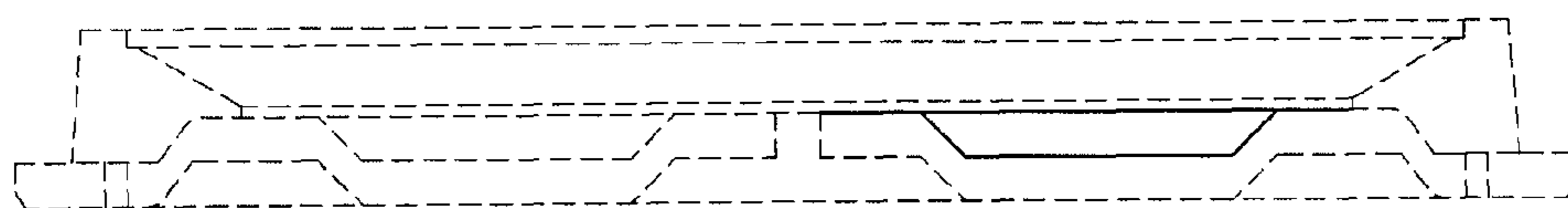


FIG. 6